

# MECHANICAL CASE OUTLINE

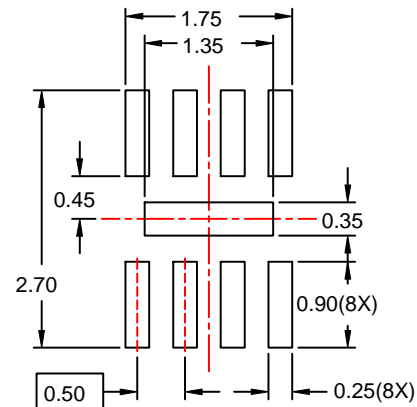
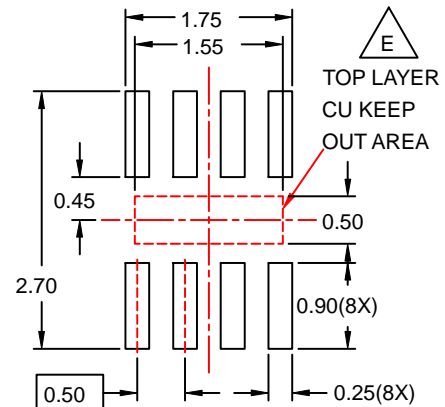
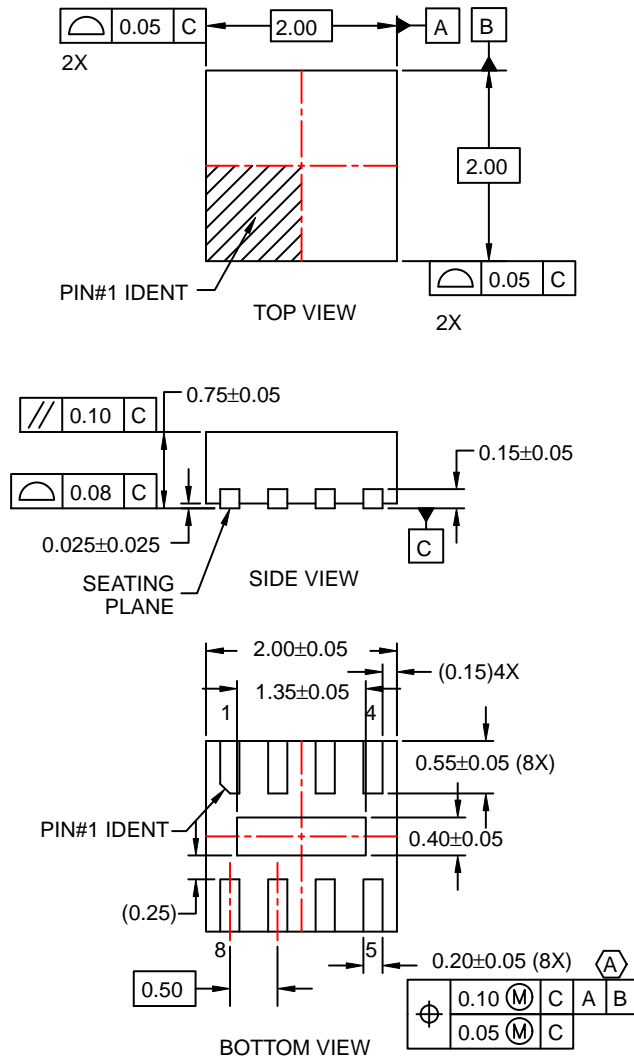
## PACKAGE DIMENSIONS

ON Semiconductor®



**WDFN8 2x2, 0.5P**  
CASE 511DL  
ISSUE O

DATE 31 JUL 2016



**RECOMMENDED LAND PATTERN**  
(NSMD PAD TYPE)

**NOTES:**

- A. PACKAGE CONFORMS TO JEDEC MO-229, VARIATION WCCE EXCEPT WHERE NOTED.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 2009.
- D. LAND PATTERN RECOMMENDATION IS EXISTING INDUSTRY LAND PATTERN.
- E. IF CENTER PAD IS NOT SOLDERED TO, NO EXPOSED METAL IS ALLOWED IN THE TOP LAYER OF THE BOARD IN THE AREA SHOWN.

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<b>STATUS:</b>	<b>ON SEMICONDUCTOR STANDARD</b>	
<b>NEW STANDARD:</b>		
<b>DESCRIPTION:</b>	<b>WDFN8 2X2, 0.5P</b>	<b>PAGE 1 OF 2</b>

